

AIDA - Academia meets Industry: Advanced interconnections for chip packaging in future detectors

Contribution ID: 52

Type: **not specified**

IMEC's activities in imagers and imager stacking

Tuesday, 9 April 2013 10:15 (15 minutes)

Primary author: DE MOOR, Piet (IMEC)

Presenter: DE MOOR, Piet (IMEC)

Session Classification: Integration of sensors with 3D electronics